

# **OUR CHEMISTRY IS EPOXY SYSTEMS**

# STRUCTURAL ADHESIVES





# **METAL PASTE ADHESIVE / 215**

Thixotropic paste which cures at room temperature and has superior strength up to 350°F.



#### **HI-TEMP ADHESIVE / 210**

Designed for aerospace repair applications for laminating, injection and coating. This system has elevated temperature strength for bonding materials together by surface attachment.



# **SUPERIOR ADHESIVE COMPOUND / 265**

Designed with low viscosity and good flow properties. It produces flexible and very strong bonds to metals, plastics and other difficult substrates, while maintaining good thermal shock resistance and very high peel strength.



#### **BOND GAP ADHESIVE / 155**

A structural aluminum filled thixotropic system with a very high glass transition temperature (Tg). Ideal for adhesion, void filling and general repair.



## **HI-STRENGTH TUFF BOND / 250**

A structural non-sag adhesive designed for those hard to bond substrates such as nylon, PTFE and stainless steel. It has high thermal shock and impact resistance.



### HI-STRENGTH TUFF BOND / 251

A structural adhesive for bonding with very high lap shear and peel strength. Designed for all substrates with hard to bond surfaces. Meets Navy drawing under NSN 8040-01-137-8418.



#### **FLEX TUFF ADHESIVE / 575**

A structural adhesive paste with 5 mil glass beads for a controlled bond line in adhesive applications. Material has a high glass transition temperature (Tg) with high flexibility.

For more information on this or other epoxy resin systems call us